



Test Run Details

Show details of selected Test Run associated with registered compon...

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ModuleQC::PixelFailureTest

Basic Properties


INSTITUTE	✓
 Tokyo Institute of Technology	TITECH
TEST DATE	
13.11.2020 19:31	
UPLOADED	
Data from server cannot be loaded.	
RUN NUMBER	
...	
TEST TYPE	
 ModuleQC::PixelFailureTest	PIXEL_FAILURE_TEST

Associated Components



 Front-end Chip - RD53A

20UPGFC9999999



Tested at stage: Test after bump bonding on module

Properties

QC stage	
MODULEWIREBONDING	
Results	
Noisy	0
High ENC	452
Tuning Bad ToT	0
Tuning Bad Threshold	2105
Tuning Failed	255
Analog Bad	12350
Analog Dead	11792
Digital Bad	0
Digital Dead	0

Defects



Attachments



std_digitalscan_datafiles.zip	▼
std_digitalscan_configfiles.zi...	▼
std_analogscan_datafiles.zip	▼
std_analogscan_configfiles.zip	▼
std_thresholdscan_datafiles.zi...	▼
std_thresholdscan_configfiles....	▼
std_totscan_datafiles.zip	▼
std_totscan_configfiles.zip	▼
std_noisescan_datafiles.zip	▼
std_noisescan_configfiles.zip	▼

Comments

